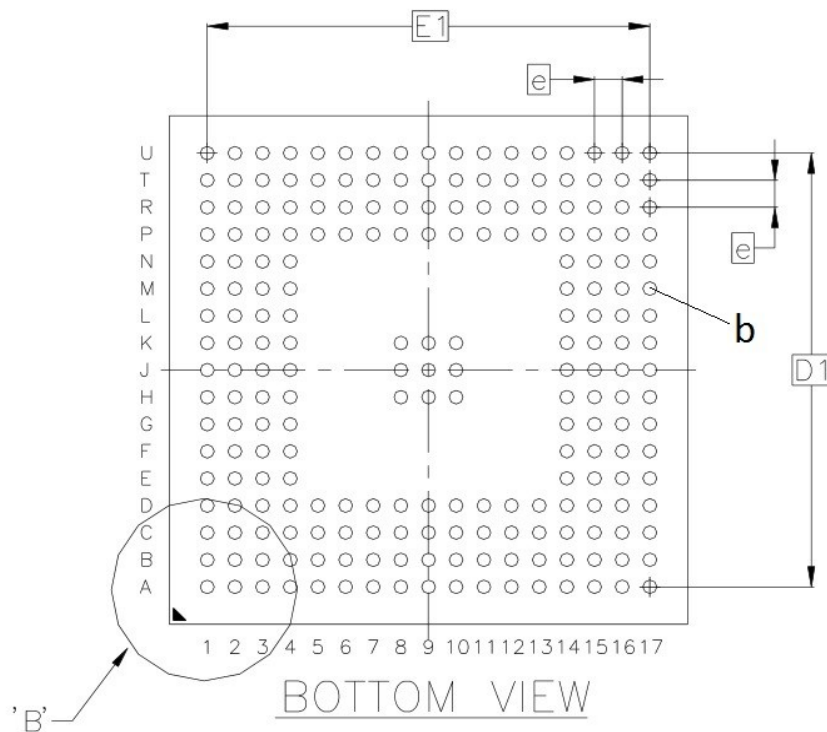


BGA217 0.8mm - stencil

Units		MILLIMETERS		
Dimension Limit		MIN	NOM	MAX
Contact Pitch	e	0.80		
Contact Pad Spacing	E1		12.80	
Contact Pad Spacing	D1		12.80	
Contact Pad diameter	b		0.40	

Top View (SMD Footprint)



Stencil dimensions: 38mm x 28mm

Thickness: 100-127 μ m

Material: stainless steel or nickel silver

Manufacturing processes: lasering or chemical etching

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